DIE BONDER

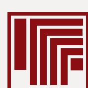
T-3002-FC3

MICRO ASSEMBLY

T-3002-FC3

The T-3002-FC3 series is Tresky's most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the FC3 incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the FC3 platform is the industry's most sophisticated system in its class.
The T-3002-FC3 is equiped with Tresky's die ejector system for pick-up from wafer.

- True Vertical Technology™
- Ultra precise bond-height control
- Unique pick-up from wafer
- Multi functional software



TRESKY

Dr. TRESKY AG Switzerland Email: tresky@tresky.com www.tresky.com

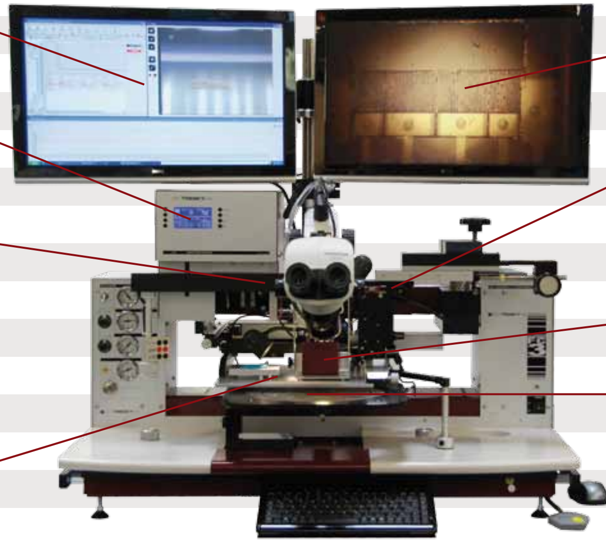
Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bonding force control.

APPLICATIONS:

Die Attach, Die Sorting, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn, ...), ...

FEATURES AND OPTIONS:

- Interface for temperature profile and video imaging
- Programmable Z-Drive with Bonding Force Control
- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...
- XY placement stage supporting: Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates



- HD Image of Beam Splitter Optics (Flip-Chip09mpaHD)
- Flip-Chip09mpa Beam Splitter with (multi point alignment) » 1µm placement accuracy
- Process Inspection Camera
- Pick-up from Wafer with Tresky's patented die ejector system, especialy suitable for all kind of Si, GaAs and InP dies down to 30µm thickness

TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g (other force ranges available)
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	10µm; 1µm with high accuracy beam splitter (Flip-Chip09mpa)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

HEADQUATERS

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